

App. No. 10/754,416
Office Action Dated May 3, 2006

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Amendments to the Specification

Title:

Please amend page 1, lines 1-2 as follows:

METHOD OF MANUFACTURING A DOUBLE-SIDED CIRCUIT BOARD
ELECTRICALLY INSULATING MATERIAL, CIRCUIT BOARD AND METHOD FOR
MANUFACTURING THE SAME

Please insert the following paragraph at page 1, line 9:

CROSS REFERENCE TO RELATED DOCUMENTS:

This application is a Division of U.S. Application No. 09/956,205, filed on 9/18/01, US Patent No. 6,734,375, which claims the benefit of Japanese Patent Application No. 2000-282120, filed on 9/18/00.